

Inovace vzdělávání v chemii na PFF MU
 Projekt CZ.1.07/2.2.00/07.0436 v rámci OP Vzdělávání pro konkurenceschopnost
 předmět „Trendy v analytické chemii“

Čisté prostory Čisté laboratoře

Laboratoře pro stopovou analýzu

Bohumil Dočekal
 Ústav analytické chemie AVČR, v.v.i., Brno

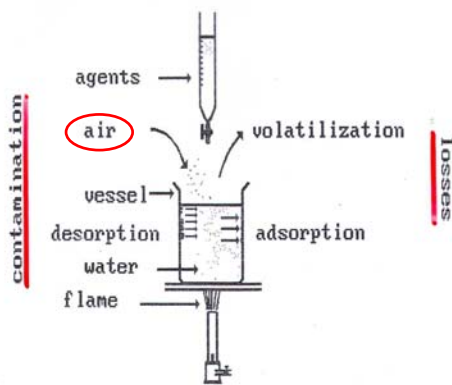
iac
 brno



Problematika stopové a ultrastopové prvkové analýzy

- hlavní a minoritní složky $10^0 - 10^{-2} \%$
- stopové příměsi $\approx 10^{-4} \%$ (ppm)
- ultrastopové příměsi $\leq 10^{-7} \%$ (ppb)

Zdroje kontaminace a ztráty analytu

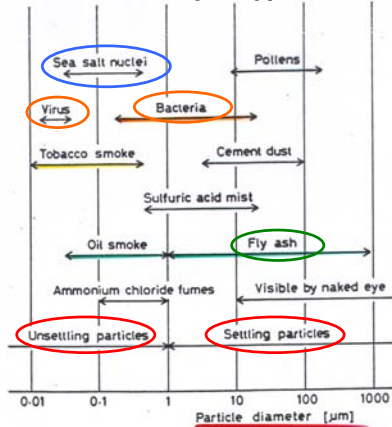


Zastoupení prvků v zemské kůře

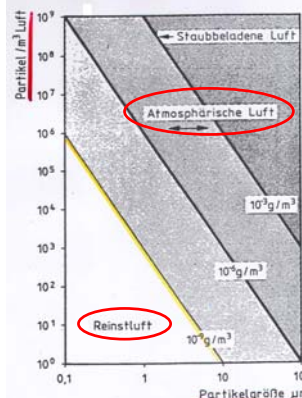
Element	%	$10^{-2} \%$	$10^{-3} \%$	$10^{-4} \%$	$10^{-5} \%$
O	46,4	Tl 57	Ni 7	Th 9	J 5
Si	28,2	H 14	Zn 7	Sm 6	Tl 4,5
Al	8,2	Mn 10	Ce 6	U 2,7	Cd 2
Fe	5,6	P 10	Co 2,5	Sn 2	Hg 1,8
Ca	4,2	S 2,6	Li 2	Ta 2	Bi 1,7
Na	2,4	C 2,0	N 2	As 1,8	Ag 0,7
Mg	2,3	Zr 1,6	Pb 1,2	Mo 1,5	Se 0,5
K	2,1	Cl 1,3	B 1	W 1	Au 0,04

R. S. Taylor, Geochim. Cosmochim. Acta 28, 1273 (1964)

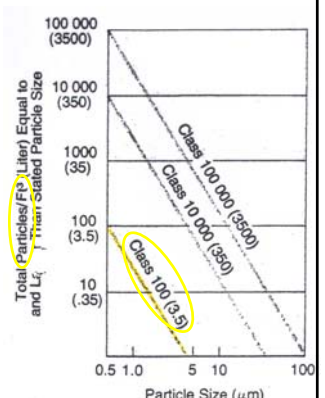
Velikost částic některých typů aerosolů



Vztah mezi počtem částic v objemové jednotce znečištěného vzduchu a jejich hmotnostní koncentraci



Limity přípustné distribuce velikosti částic dle US Federal Standard 209b



Třídy čistoty dle norem US Federal Standard 209b a VDI 2083, list 1

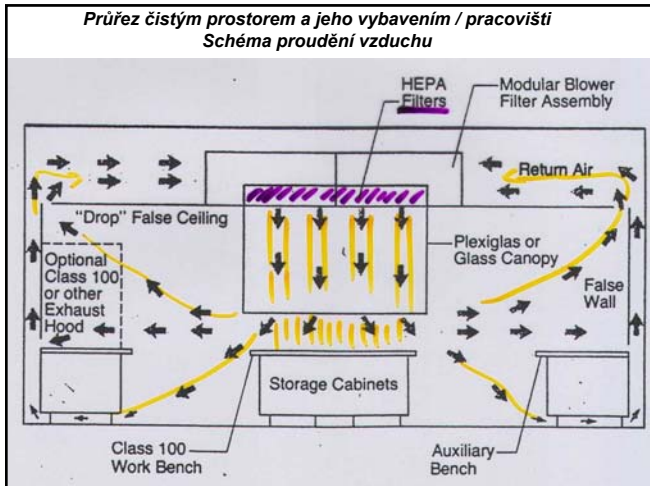
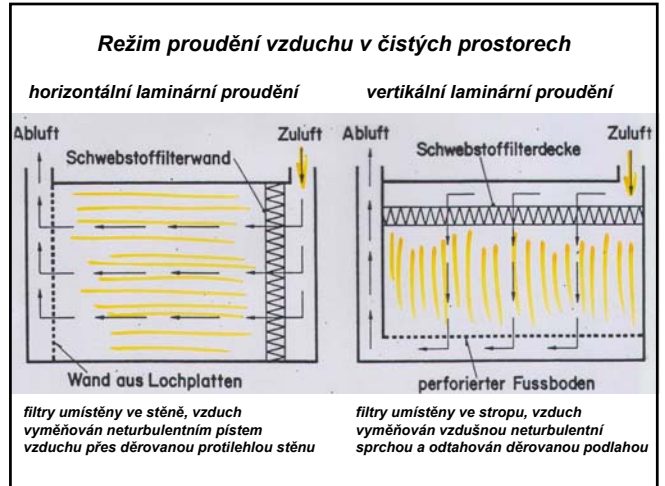
Die Reinheitsklassen gemäß den Festlegungen des US Federal Standard 209b sowie von VDI 2083, Blatt 1.

Reinheitsklasse		maximal zulässiger Staubpegel			
US Fed. Std. 209b	VDI 2083 Bl. I	Teilchen pro l ³ Luft		Teilchen pro m ³ Luft	
		≥ 0,5 µm	≥ 5 µm	≥ 0,5 µm	≥ 5 µm
100	3	100	< 10*	4 × 10 ⁶	—**
1 000	4	1 000	< 10*	4 × 10 ⁵	0,03 × 10 ⁶
10 000	5	10 000	70	4 × 10 ⁴	0,03 × 10 ⁶
100 000	6	100 000	700	4 × 10 ³	0,03 × 10 ⁶

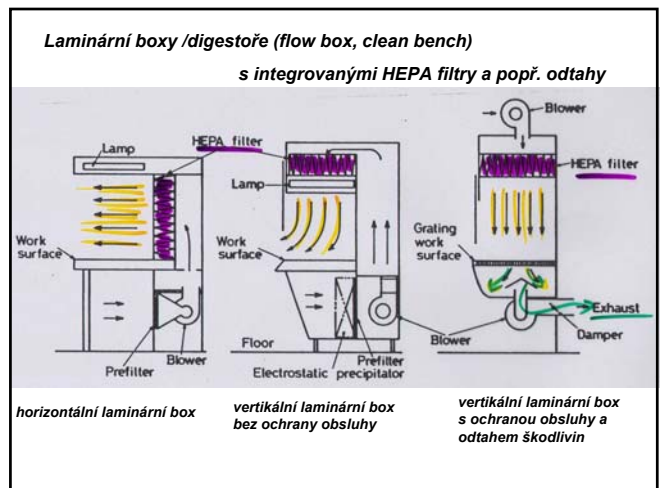
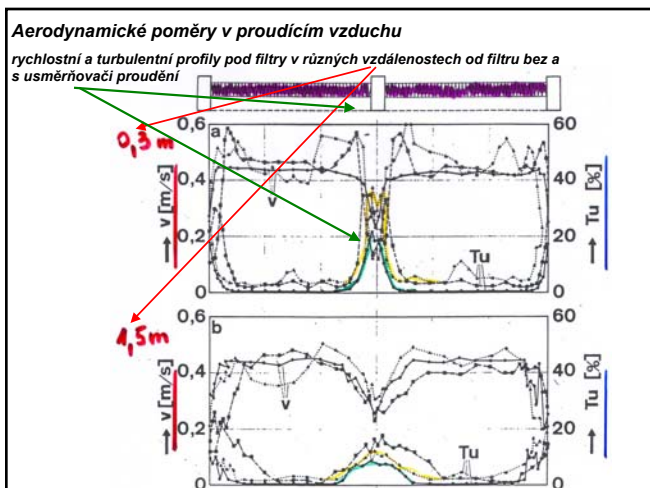
* aus statistischen Gründen nicht bewertet
 **Luwa-Vorschlag für einen erweiterten, den heutigen und den voraussehbaren Bedürfnissen der Reinraumtechnik entsprechenden US Federal Standard 209b.

Reinheitsklasse nach		Partikel pro Kubikfuß			
VDI 2083 Blatt I	US Fed. Std. 209b	≥ 0,02 µm*	≥ 0,1 µm*	≥ 0,5 µm	≥ 5 µm
0*	0,1*	10 ²	3 × 10 ³	10 ^{-1**}	***
1*	1*	10 ³	3 × 10 ⁴	10 ^{0**}	***
2*	10*	10 ⁴	3 × 10 ⁵	10 ^{1**}	***
3	100	10 ⁵	3 × 10 ⁶	10 ^{2**}	***
4	1 000	10 ⁶	3 × 10 ⁷	10 ^{3**}	7 × 10 ²
5	10 000	10 ⁷	3 × 10 ⁸	10 ^{4**}	7 × 10 ³
6	100 000	10 ⁸	3 × 10 ⁹	10 ^{5**}	7 × 10 ⁴

* Neue Reinheits- bzw. Partikelgrößenklassen
 ** Angabe nur sinnvoll zum Zweck der Klassendefinition (siehe auch ***)
 *** Angabe aus statistischen Gründen für Messzwecke nicht sinnvoll
 **** Angabe nicht relevant für die Festlegung von Reinheitsanforderungen



- Koncepce čistého prostoru**
- účel (pro jaké operace ?, ochrana výrobku/vzorku, ochrana personálu, resp. obojí – provoz mikroelektronického, farmaceutického průmyslu, speciální laboratoře pro stopovou analýzu a klinickou biochemii, operační sály)
 - operace (vážení, příprava vzorku, rozklad vzorku, měření, chirurgický zákrok)
 - jednotlivá pracoviště (třída čistoty, priorita operací, GLP/GMP, ocenění rizika kontaminace/ohrožení obsluhy)
 - hospodárnost provozu (spotřeba energie na topení/chlazení, zvlhčování, recyklace vzduchu, odvod balastního tepla a toxických výparů/zplodin)
 - technologie (čistota vzduchu, počet výměn vzduchu v místnosti za určitou dobu, filtrace vzduchu, řízení teploty/vlhkosti vzduchu, odvod balastního tepla z technologií, odtah nebezpečných zplodin, prostorové možnosti, servisní prostory, mezioperační sklady, přetlakový režim a tlakový spád mezi jednotlivými součástmi čistých provozů)



Čisté prostory



Čisté prostory, operační sály, laboratoře



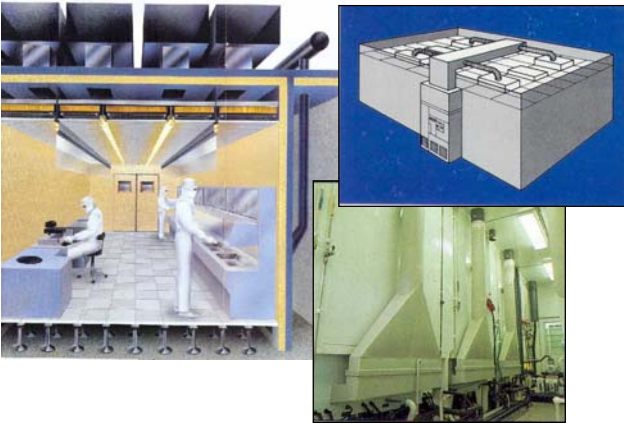
RIFA Ab, Stockholm, Sweden

MEV, Budapest, Hungary

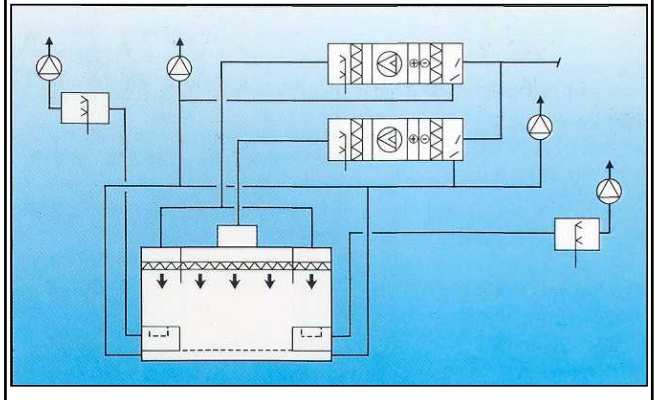


Rheumatism Foundation Hospital, Helsinki, Finland

Vzduchotechnická zařízení a servisní prostory

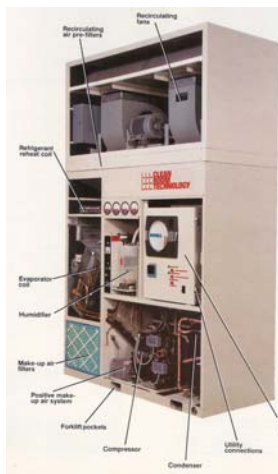


Vzduchotechnická zařízení – filtrace, regulace teploty a vlhkosti vzduchu

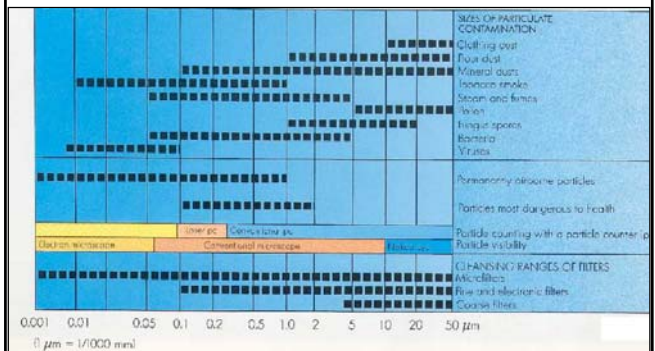


Vzduchotechnická zařízení –

**ventilace
filtrace
regulace teploty a
vlhkosti vzduchu**



Vzduchotechnická zařízení – filtrace

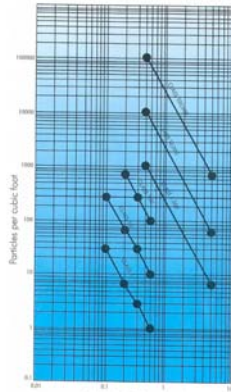


Filtrace vzduchu

Table 3 Class Limits, in Particles per Cubic Foot of Sizes Greater than or Equal to Size Shown

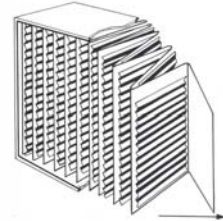
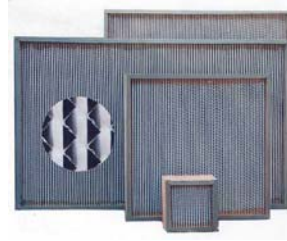
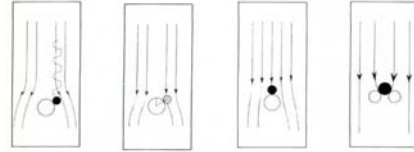
Class	Particle size, micrometers			
	0.1	0.2	0.3	0.5
1	35	7.5	3	1
10	350	75	30	10
100	...	750	300	100
1000	1000
10000	10000
100000	100000
				700

Federal Standard 209B only defines certain environmental requirements in general terms, such as
 - overpressure more than 12 Pa
 - temperature 22 °C ± 3 °C
 - humidity 40 % ± 10 %

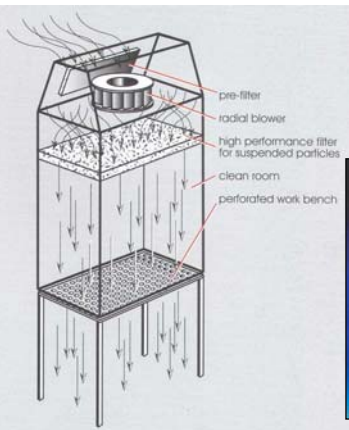


Particle size (Micrometer)
 Federal Standard 209C
 Proposed Revision,
 April 1986

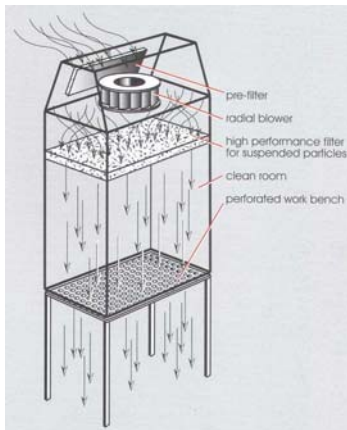
Filtrace vzduchu (absolutní filtry HEPA – 99.99%, ULPA – 99.9999%)



Laminární boxy



Laminární boxy



Pracovní buňky



Pracovní buňky



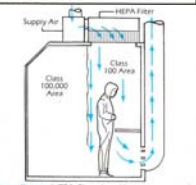
ULPA/All Totally contained laboratory work area Hazardous waste analysis, toxicology, chemical and acid fume ventilations, safety stations, explosion proof and flammable storage



Isolation Room Dust/draft free, temperature controlled modules Microscopy, clinical chemistry, forensic chemistry, spectroscopy and chromatography.



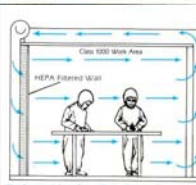
Environmental Room (Temperature and humidity controlled environment) Computer applications, pathology, microbiology, material storage, ASTM testing



Clean Room (HEPA filtered positive pressure work area) Pharmaceutical and cosmetic analysis, biomedical procedures, particle technology, analytic recording

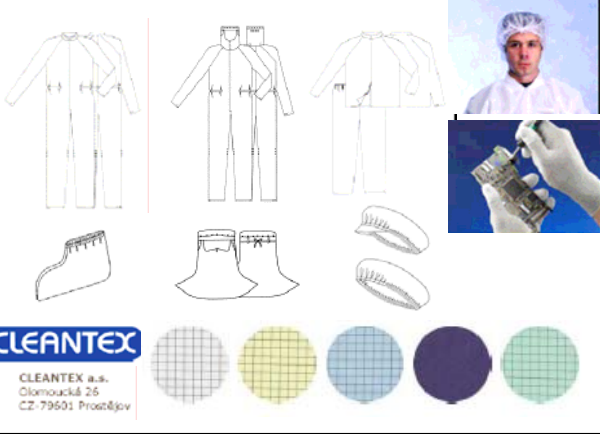


Micro-Electronic Assembly Continuous clean room systems Quality control and testing, electronic packaging, robotics, and static protection, HEPA filtered positive pressure work area

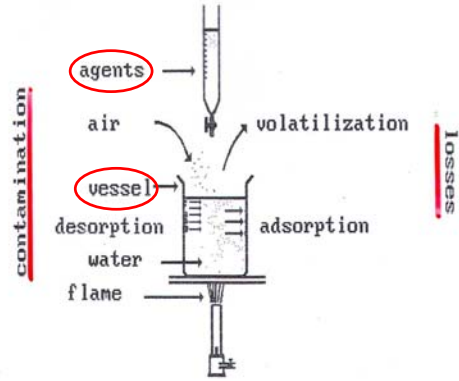


Horizontal Laminar Flow Room (Tunnel design enables air to move through the work area and exhaust at opposite end) Advantageous for small work areas and where using clearance is a factor

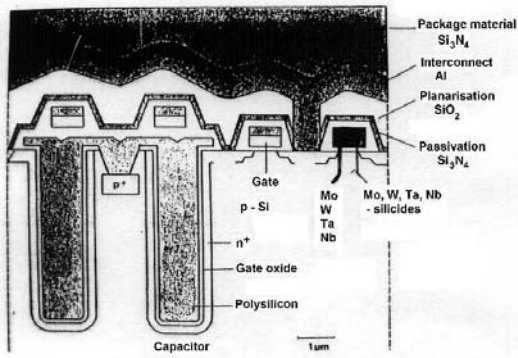
Pracovní oděvy, návleky, rukavice, čepice, roušky



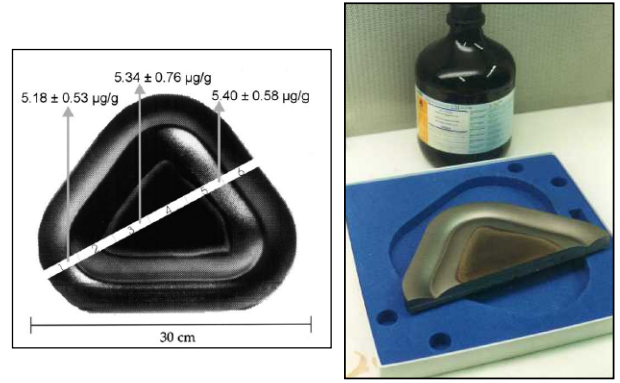
Zdroje kontaminace a ztráty analytu



Microelectronic cell and its materials



6N Titanium sputtering target for VLSI-technology



Example

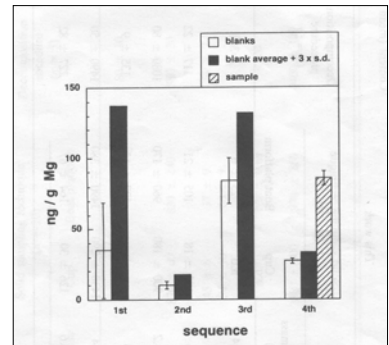
refractory metals in VLSI-technology (gate material)
6N high purity grade molybdenum (99.9999 %)
(sputtering targets for plasma technology)

requirements:

- **heavy metals** (Cu, Fe, Mn, Ni, Pb, Zn) - **max. 10² ppb** (junction leaks)
- **mobile ions** (Li, Na, K, Mg, Ca ...) - **max. 10¹ ppb** (additional doping effects)
- **radioactive species** (U, Th ..) - **below 10⁰ ppb** (ionization effects)

Example - determination of Mg in hp Mo, hp MO_3
wet decomposition in $HNO_3 + H_2O_2$ under clean-bench conditions - class 100, n = 5

LODs (ppb)	
Ca	500
K	200
Mg	100
Na	200



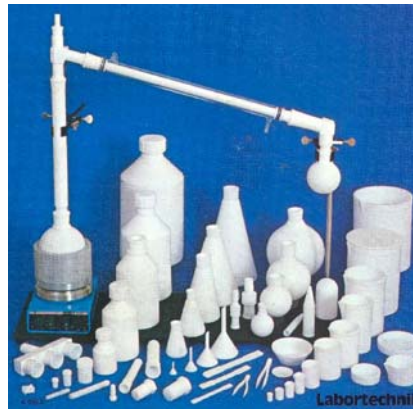
Materiály – odolnost, vlastnosti

Container materials commonly used in inorganic trace analysis

Material	Maximum service temperature (°C)	Poor chemical resistance [16] to	Permeability
Pyrex* (borosilicate glass)	600	Hydrofluoric acid, Conc. phosphoric acid, Sodium hydroxide solution	None
Vycor** (high-silica glass)	900	Hydrofluoric acid, Conc. phosphoric acid, Sodium hydroxide solution	None
Vitreous silica	1100	Hydrofluoric acid, Conc. phosphoric acid, Sodium hydroxide solution	None
Platinum	1500	Aqua regia	None
Glassy carbon [17]	600	None	None
Polyethylene	80 (High-pressure process)	Organic solvents, Conc. nitric acid, Conc. sulfuric acid	Permeable
	110 (Low-pressure process)		
Polypropylene	130	Organic solvents, Conc. nitric acid, Conc. phosphoric acid, Sodium hydroxide solution	Permeable
Teflon (polyfluorocarbon)	250	None	Permeable

* SiO₂ 81, B₂O₃ 13, Na₂O 4, K₂O 0.5, Al₂O₃ 2 (wt%)
 ** SiO₂ 96, B₂O₃ 3, Al₂O₃ 0.5 (wt%)

Materiály – PTFE, PP, PFA, PC



Materiály – obsah nečistot

Impurities in inorganic container materials – examples

Concentration level (µg/g)	Pyrex [18]	Vycor [18]	Vitreous silica [18]	Platinum [12]	Glassy carbon [17]
10 ³ – 10 ⁵	Ca, Cl, Fe, Mg, Zr	As, Fe, Mg, Na, Ti, Zr			
10 – 10 ²	F, Ga, Hf, Li, Mn, Ni, S, Sr, Ti, V	Ca, Cl, Hf, K, Zn	Ca, Fe, Mg, Zn	Au, Pd	Ca, Si, Sn, Ti
1 – 10	As, Ba, Bi, Cr, Cu, P, Pb, Sb, Se, Y, Zn	Ag, Cu, F, Ga, Li, Mn, Ni, S, Sb, Sn	Ag, Al, Cl, Cu, F, Ga, Hf, K, Li, Na, Ni, Ti, Zr	Ag, Cu, Fe, Rh, Ti	Al, Fe, V

Materiály – čištění nádobek



Figure 2. Twenty-position component rack with PTFE-based glass rods.

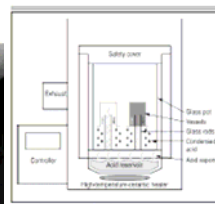
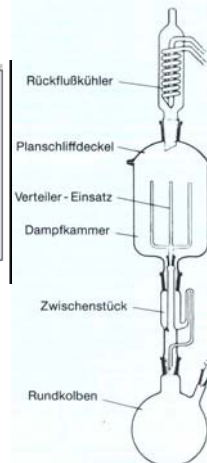
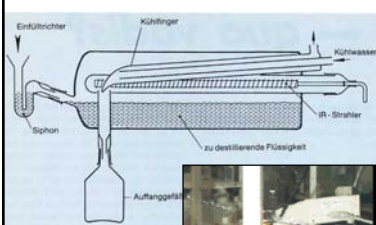


Figure 4. Schematic of the TraceClean's sub-boiling acid cleaning process.



Čisté chemikálie (voda, Suprapure, sub-boiled)



podvarová destilace

Table 1. Comparison of trace metal contamination in select high-purity nitric acids. Concentration is shown in µg/g.

Trace impurity	Degussa single-distilled ^a	Degussa double-distilled ^a	Fisher Optima ^b	Baker Ultra ^c
Be	<2	<1	<5	<20
Mg	<195	<42	<5	<100
Al	<157	<147	<20	<300
Ca	<900	<157	<50	<300
Ti	<99	<8.1	<20	<100
V	<51	<11	<1	<20
Cr	<118	<4.6	<10	<50
Mn	<9.7	<2.1	<1	<20
Fe	<1000	<210	<20	<300
Co	<75	<1	<1	<100
Ni	<155	<23	<10	<100
Cu	<58	<21	<2	<50
Zn	<261	<49	<2	<100
As	<3	<0.9	<10	<100
Se	<3.9	<1.2	<10	Not listed
Sr	<12	<1.2	<1	<10
Mo	<7.1	<0.4	<1	<100
Ag	<46	<1.5	<1	<10
Cd	<8.1	<1.8	<1	<20
Sn	<22	<9.1	<10	<100
Sb	<6.1	<0.5	<10	<100
Ba	<25	<3.5	<1	<20
Tl	<2.6	<0.9	<1	<10
Pb	<10	<2.5	<1	<100

^aConcentration expressed as the upper limit of the 99% confidence limit of the measured result (n = 4).
^bFrom reference 7.
^cFrom reference 8.

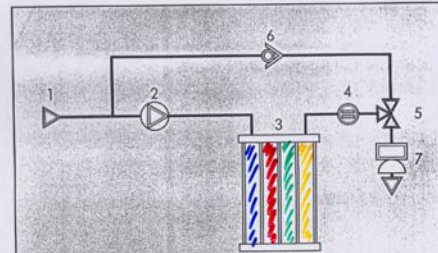
Čisté chemikálie (voda, Suprapure, sub-boiled)

vysokočistá voda - MQ

Water Purification System

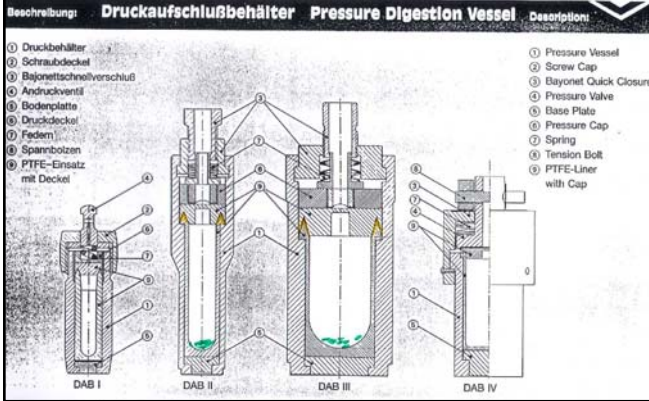
Flow Schematic

- Inlet - 1
- Pump - 2
- Purification pack - 3
- Resistivity sensor - 4
- 3-way valve (manual) - 5
- Check valve - 6
- Millipak Filter Unit - 7



Tlakové rozklady vzorků

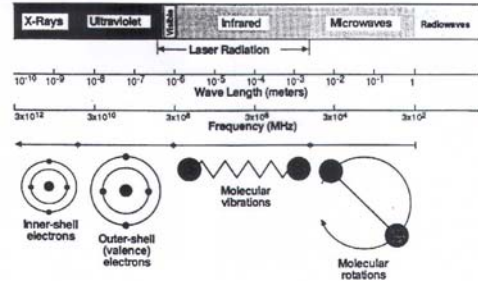
klasické autoklávy



Mikrovlnné systémy

Theory

Microwaves are electromagnetic energy. Microwave energy is a nonionizing radiation that causes molecular motion by migration of ions and rotation of dipoles, but does not cause changes in molecular structure. Microwave energy has a frequency range from 300 to 300,000 MHz (Figure 2.1). Four fre-



Mikrovlnné systémy

absorpce MW

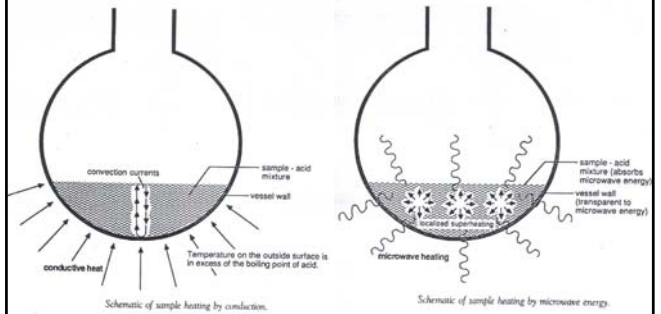
Dissipation Factor of Different Materials

Material	Temperature (°C)	Tangent ^a δ (× 10)
Water	25	1570.0
Fused Quartz	25	0.6
Ceramic F-66	25	5.5
Porcelain No. 4462	25	11.0
Phosphate Glass	25	46.0
Borosilicate Glass	25	10.6
Corning Glass No. 0080	25	126.0
Plexiglass	27	57.0
Nylon 66	25	128.0
Polyvinyl Chloride	20	55.0
Polyethylene	25	3.1
Polystyrene	25	3.3
Teflon PFA	25	1.5

^aMeasurements made at 3000 MHz.

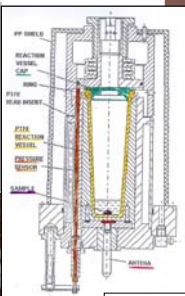
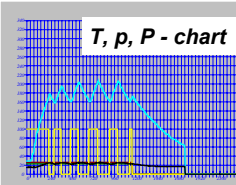
Mikrovlnné systémy

ohřev klasický vs. MW



Mikrovlnné systémy

Uniclever microwave digestion unit Plazmatronika,
(Wroclaw, Poland)
(max.power 100 W, 4.5 MPa, 250°C)



fokusované pole

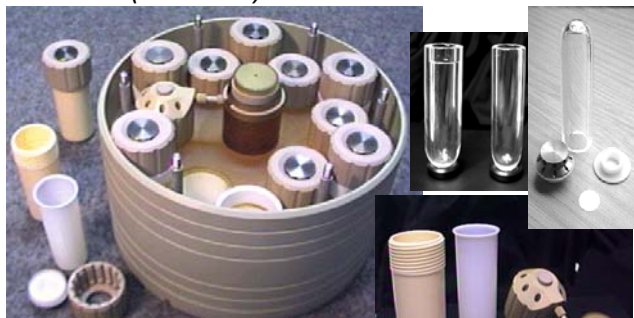


Mikrovlnné systémy

Multiwave (Anton Paar)



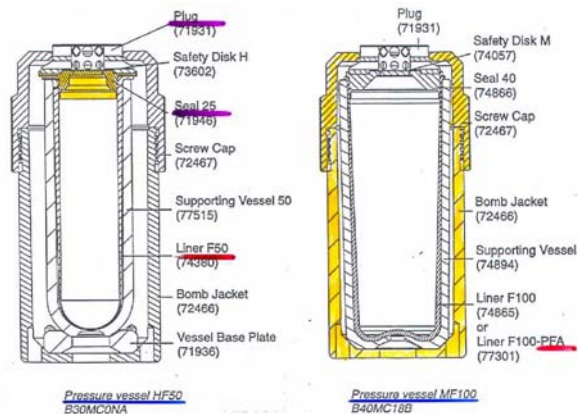
**Mikrovlnné systémy
MultiWave (Anton Paar)**



tlakové nádoby

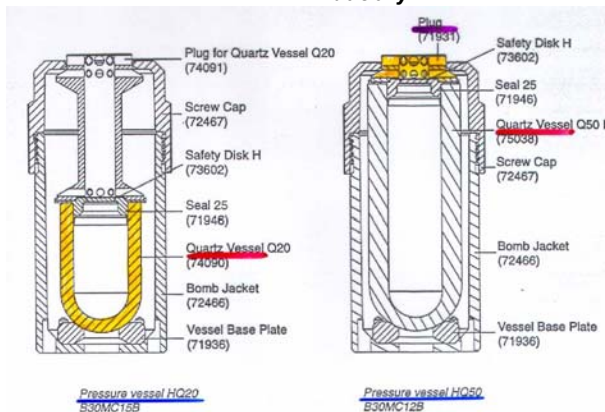
Mikrovlnné systémy

nádoby



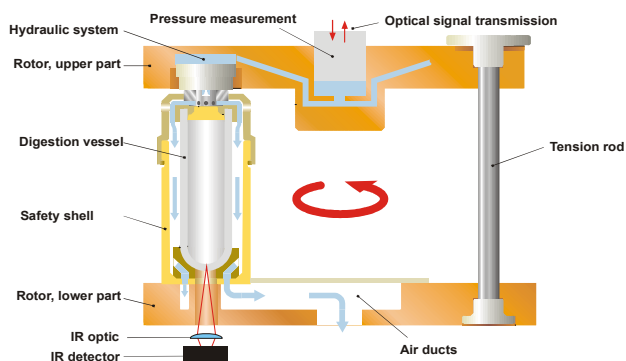
Mikrovlnné systémy

nádoby



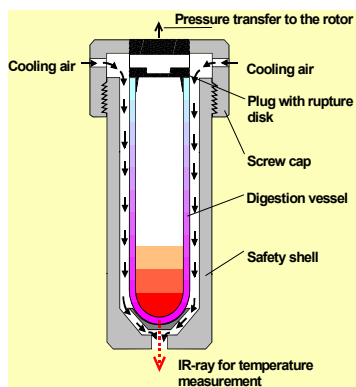
Mikrovlnné systémy

Multiwave (max. 1000 W, bezpulzní regulace)



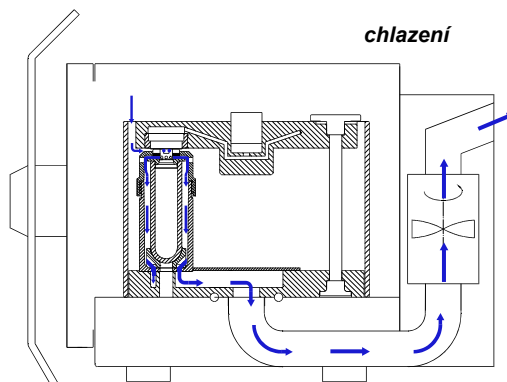
Mikrovlnné systémy

Multiwave



Mikrovlnné systémy

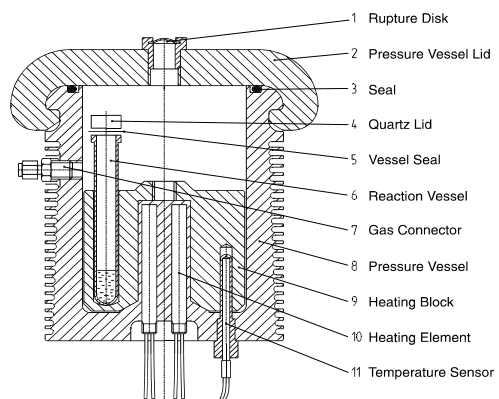
chlazení



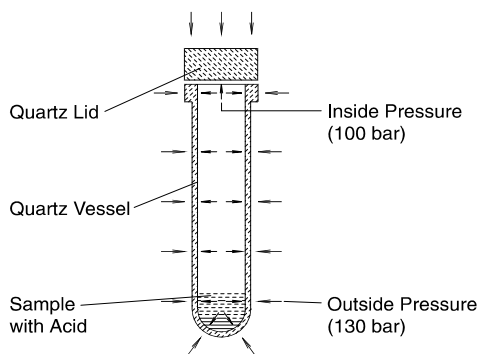
High Pressure Asher (Anton Paar)



High Pressure Asher (Anton Paar)



High Pressure Asher (Anton Paar)



**iac
brno**

Bohumil Dočekal
Institute of Analytical Chemistry, Czech Academy of Sciences v.v.i.
Veveří 97, CZ 60200 Brno, Czech Republic
e-mail: docekal@iach.cz